

• General Description

The AGM412MPA combines advanced trench MOSFET technology with a low resistance package to provide extremely low $R_{DS(ON)}$.

This device is ideal for load switch and battery protection applications.

Features

- Advance high cell density Trench technology
- Low R_{DS(ON)} to minimize conductive loss
- ■Low Gate Charge for fast switching
- ■Low Thermal resistance
- ■100% Avalanche tested
- ■100% DVDS tested

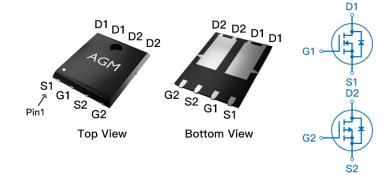
Application

- ■MB/VGA Vcore
- ■SMPS 2nd Synchronous Rectifier
- ■POL application
- ■BLDC Motor driver

Product Summary

BVDSS	RDSON	ID
40V	10mΩ	40A
-40V	12mΩ	-45A

PDFN5*6 Pin Configuration



Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
AGM412MPA	AGM412MPA	PDFN5*6	330mm	12mm	3000

Table 1. Absolute Maximum Ratings (TA=25°C)

		Rating		
Symbol	Parameter	N-Ch	P-Ch	Units
V _{DS}	Drain-Source Voltage (V _{GS} =0V)	40	-40	V
V_{GS}	Gate-Source Voltage (V _{DS=} 0V)	±20	±20	V
	Drain Current-Continuous(TC=25℃) (Note 1)	40	-45	А
I_D	Drain Current-Continuous(TC=100°C)	35	-37	А
IDM (pluse)	Drain Current-Pulsed (Note 2)	160	-180	Α
	Total Power Dissipation(TC=25℃)	25	25	W
P_D	Total Power Dissipation(TC=100°C)	10	10	W
EAS	Avalanche energy (Note 3)	72	196	mJ
TJ,TSTG	Operating Junction and Storage Temperature Range	-55 To 150	-55 To 150	°C

Table 2. Thermal Characteristic

Symbol	Parameter	Тур	Max	Unit
R ₀ JA	Thermal Resistance Junction-ambient (Steady State) ¹		20	°C/W
R _{0JC}	Thermal Resistance Junction-Case ¹		5.0	°C/W



Table 3. N- Channel Electrical Characteristics (TJ=25℃unless otherwisenoted)

Symbol	- Channel Electrical Characteris Parameter	Conditions	Min	Тур	Max	Unit
On/Off State	es					
BVDSS	Drain-Source Breakdown Voltage	VGS=0V ID=250μA	40			V
IDSS	Zero Gate Voltage Drain Current	VDS=40V,VGS=0V			1	μΑ
IGSS	Gate-Body Leakage Current	VGS=±20V,VDS=0V			±100	nA
VGS(th)	Gate Threshold Voltage	VDS=VGS,ID=250μA	1.2		2.2	V
gFS	Forward Transconductance	VDS=5V,ID=10A		9		S
RDS(on)	Drain-Source On-State Resistance	VGS=10V, ID=20A		10	14	mΩ
1.00(011)	Drain Course on State Hosiotanes	VGS=4.5V, ID=10A		13	18	mΩ
Dynamic C	Characteristics					
Ciss	Input Capacitance			1152		pF
Coss	Output Capacitance	VDS=20V,		85		pF
Crss	Reverse Transfer Capacitance	VGS=0V, F=1MHZ		73		pF
Rg	Gate resistance	VGS=0V, VDS=0V,f=1.0MHz		2.7		Ω
Switching	Times					
td(on)	Turn-on Delay Time			6.0		nS
tr	Turn-on Rise Time	VGS=10V,VDS=25V,		12		nS
td(off)	Turn-Off Delay Time	RL=0.75 Ω ,RGEN=6 Ω		18		nS
tf	Turn-Off Fall Time			7		nS
Qg	Total Gate Charge			17		nC
Qgs	Gate-Source Charge	VGS=10V, VDS=25V, ID=5A		8		nC
Qgd	Gate-Drain Charge			10		nC
Source-Dr	ain Diode Characteristics					
ISD	Source-Drain Current(Body Diode)				40	Α
VSD	Forward on Voltage	VGS=0V,IS=5A			1.2	V
trr	Reverse Recovery Time	IF=5A , dl/dt=100A/μs ,				ns
Qrr	Reverse Recovery Charge	TJ=25℃				nc

Notes 1. The maximum current rating is package limited.

Notes 2.Repetitive Rating: Pulse width limited by maximum junction temperature

Notes 3.EAS condition: TJ=25 $^{\circ}\text{C}$,VDD=25V,Vgs=10V,ID=17A,L=0.5mH,RG=25ohm



Table 3. P-Channel Electrical Characteristics (TJ=25℃unless otherwisenoted)

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
On/Off Sta	tes					
BVDSS	Drain-Source Breakdown Voltage	VGS=0V ID=-250µA	-40			V
IDSS	Zero Gate Voltage Drain Current	VDS=-40V,VGS=0V			-1	μA
IGSS	Gate-Body Leakage Current	VGS=±20V,VDS=0V			±100	nA
VGS(th)	Gate Threshold Voltage	VDS=VGS,ID=-250µA	-1.2		-2.2	V
gFS	Forward Transconductance	VDS=-5V,ID=-5A		18		S
RDS(on)	Drain-Source On-State Resistance	VGS=-10V, ID=-15A		12	16	mΩ
123(611)		VGS=-4.5V, ID=-10A		17	22	mΩ
Dynamic C	Characteristics					
Ciss	Input Capacitance	VDS=-20V,VGS=0V,		2385		pF
Coss	Output Capacitance	F=1MHZ		185		pF
Crss	Reverse Transfer Capacitance			162		pF
Rg	Gate resistance	VGS=0V, VDS=0V,f=1.0MHz		5.9		Ω
Switching	Times					
td(on)	Turn-on Delay Time			18		nS
tr	Turn-on Rise Time	VGS=-10V,VDS=-15V,		31		nS
td(off)	Turn-Off Delay Time	ID=-15A,RGEN=3.3Ω		70		nS
tf	Turn-Off Fall Time			40		nS
Qg	Total Gate Charge			30		nC
Qgs	Gate-Source Charge	VGS=-4.5V, VDS=-15V, ID=-10A		9.0		nC
Qgd	Gate-Drain Charge	- VD313V, ID10A		15		nC
Source-Dr	ain Diode Characteristics			,		
ISD	Source-Drain Current(Body Diode)				-45	А
VSD	Forward on Voltage	VGS=0V,IS=-15A			-1.28	V
trr	Reverse Recovery Time	IF=-15A , dl/dt=100A/μs ,				ns
Qrr	Reverse Recovery Charge	TJ=25℃				nc

Notes 1. The maximum current rating is package limited.

 $Notes 2. Repetitive \ Rating: Pulse \ width \ limited \ by \ maximum junction \ temperature \ Notes$

3.EAS condition: TJ=25 $^{\circ}\text{C}$,VDD=-25V,Vgs=-10V,ID=-28A,L=0.5mH,RG=25ohm



Fig.1 Power Dissipation

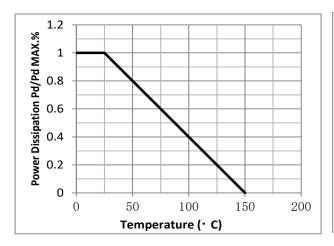


Fig.2 Typical output Characteristics

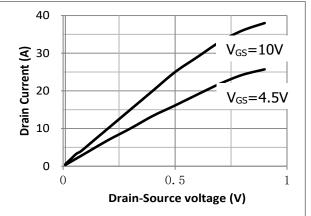
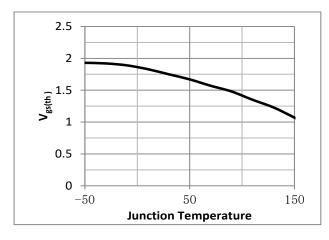


Fig.3 Threshold Voltage V.S Junction Temperature Fig.4 Resistance V.S Drain Current



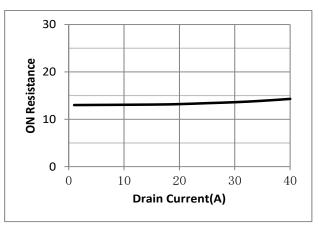


Fig.5 On-Resistance VS Gate Source Voltage

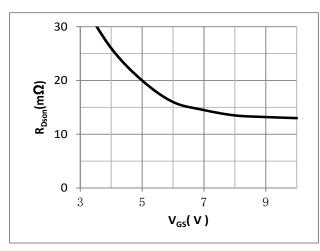


Fig.6 On-Resistance V.S Junction Temperature

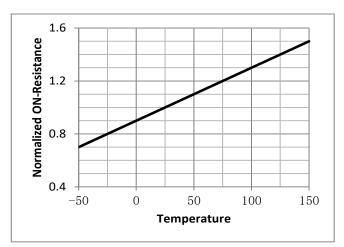




Fig.7 Switching Time Measurement Circuit

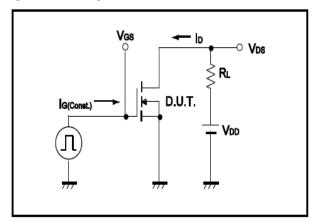


Fig.8 Gate Charge Waveform

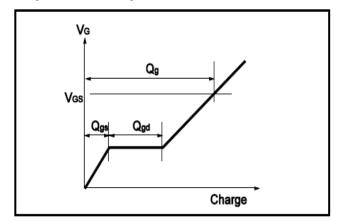


Fig.9 Switching Time Measurement Circuit

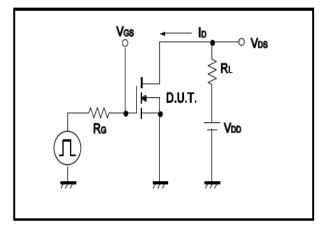


Fig.10 Gate Charge Waveform

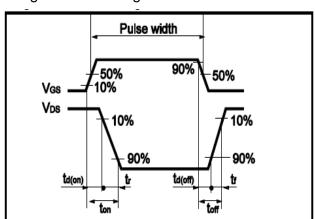


Fig.11 Avalanche Measurement Circuit

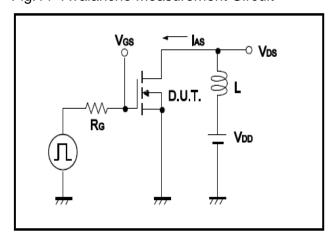


Fig.12 Avalanche Waveform

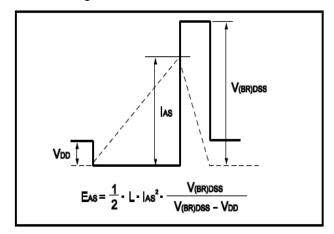




Fig.1 Gate-Charge Characteristics

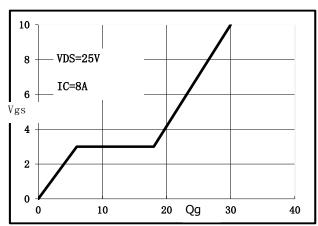


Fig.2 Capacitance Characteristics

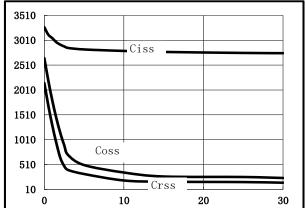


Fig.3 Power Dissipation Derating Curve

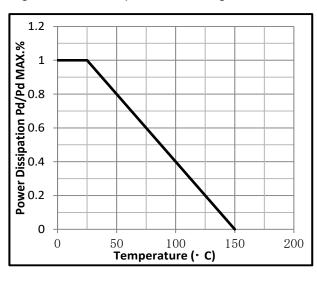


Fig.4 Typical output Characteristics

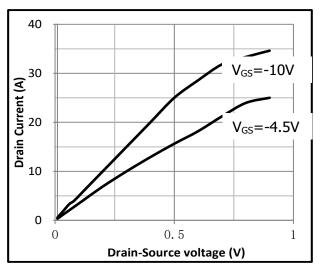


Fig.5 Threshold Voltage V.S Junction Temperature F

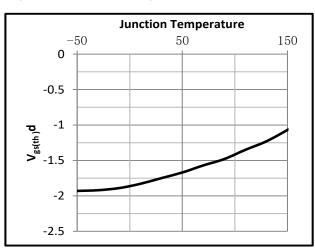


Fig.6 Resistance V.S Drain Current

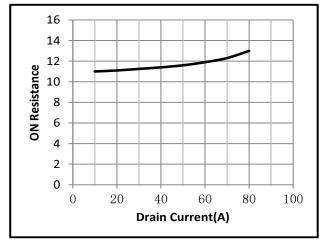




Fig.7 On-Resistance VS Gate Source Voltage

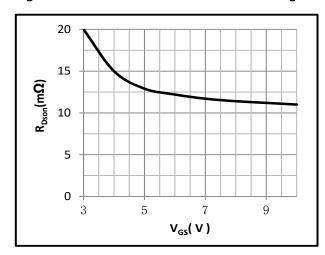


Fig.8 On-Resistance V.S Junction Temperature

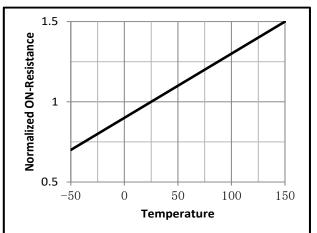


Fig.9 Switching Time Measurement Circuit

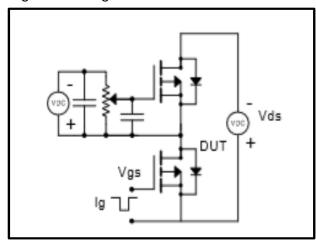


Fig.10 Gate Charge Waveform

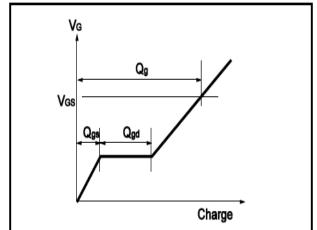


Fig.11 Switching Time Measurement Circuit

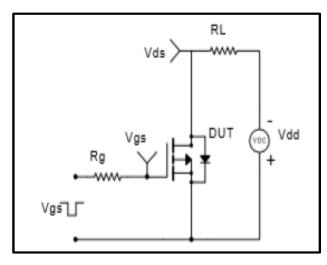
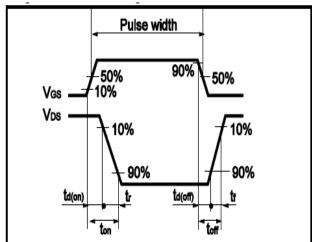
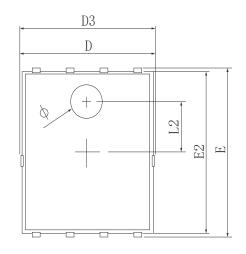


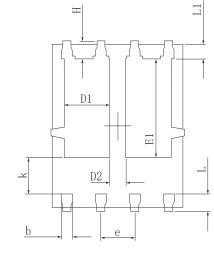
Fig.12 Gate Charge Waveform



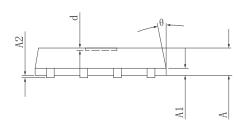


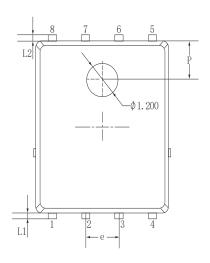
•Dimensions (PDFN5*6)

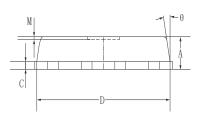


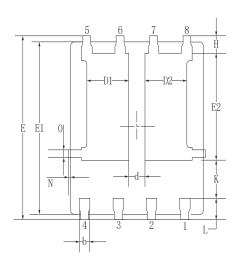


CVARDOI		MILLIMETER	!
SYMBOL -	MIN	Тур.	MAX
A	0.900	1.000	1.100
A1		0.254 REF.	
A2	0~0.05		
D	4.824	4. 900	4. 976
D1	1.605	1.705	1.805
D2	0.500	0.600	0.700
D3	4.924	5.000	5. 076
Е	5.924	6.000	6.076
E1	3. 375	3. 475	3. 575
E2	5. 674	5. 750	5.826
b	0.350	0.400	0.450
е		1.270 TYP.	
L	0. 534	0.610	0.686
L1	0. 424	0.500	0.576
L2		1.800 REF.	
k	1.190	1. 290	1.390
Н	0. 549	0. 625	0.701
θ	8°	10°	12°
Φ	1.100	1. 200	1.300
d			0.100







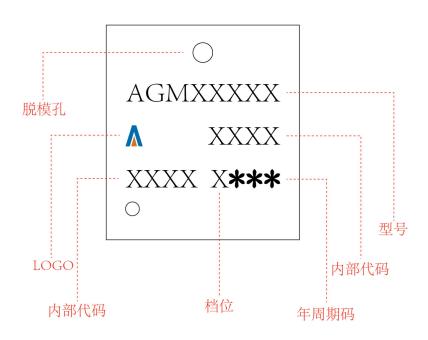


Symbol	Millitmeters			
	MIN.	NOM.	MAX.	
A	0.90	1.05	1. 20	
b	0.35	0.40	0.50	
С	0.20	0.25	0.35	
D	4.90	5. 05	5. 20	
D1/D2	1.51	1.61	1.71	
d	0.50	0.60	0.70	
Е	6.00	6. 15	6. 30	
E1	5.60	5. 75	5.90	
E2	3.47	3. 57	3. 67	
е		1. 27 BSC.		
Н	0.48	0. 58	0.68	
K	1.17	1. 27	1. 37	
L	0.64	0.74	0.84	
L1/L2	0. 20 REF.			
θ	8°	10°	12°	
M	0.08 REF.			
N	0	-	0.15	
0	0.25 REF.			
Р	1.28 REF.			
r	1. 40 REF.			

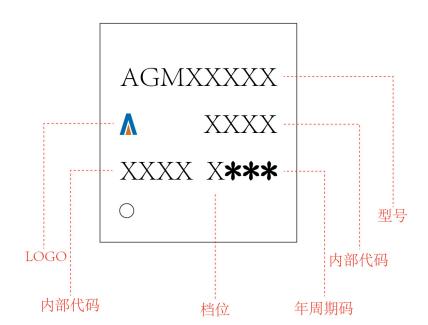


PDFN5*6 Marking Instructions:

Model1:



Model2:





Disclaimer:

The information provided in this document is believed to be accurate and reliable. However, Shenzhen Core Control Source Electronics Technology Co., Ltd. does not assume any responsibility for the following consequences. Do not consider the use of such information or use beyond its scope.

The information mentioned in this document may be changed at any time without notice.

The products and information provided in this document do not infringe patents. Shenzhen Core Control Source Electronics Technology Co., Ltd. assumes no responsibility for any infringement of any other rights of third parties. The result of using such products and information.

This document is the fifth version issued on March 20th, 2024. This document replaces all previously provided information.

It is a registered trademark of Shenzhen Core Control Source Electronics Technology Co., Ltd.

Copyright © 2017 Shenzhen Core Control Source Electronics Technology Co., Ltd. all rights reserved.